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3A, 50 - 200V Surface Mount Ultrafast Power Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Ultrafast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Monitor
- TV

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Packing code with suffix "G" means green compound (halogen-free)
- Part No. with suffix "H" means AEC-Q101 qualified
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.11 g (approximately)

KEY PARAMETERS					
PARAMETER VALUE UNI					
I _{F(AV)}	3	А			
V _{RRM}	200	V			
I _{FSM}	75	А			
T _{J MAX}	175 °C				
Package	DO-214AA (SMB)				
Configuration	Single Die				





DO-214AA (SMB)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	MUR305SB	MUR310SB	MUR315SB	MUR320SB	UNIT
Marking code on the device		MUR305SB	MUR310SB	MUR315SB	MUR320SB	
Repetitive peak reverse voltage	V _{RRM}	50	100	150	200	V
Reverse voltage, total rms value	V _{R(RMS)}	35	70	105	140	V
Forward current	I _{F(AV)}	3			Α	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	75			A	
Junction temperature	T_J	- 55 to +175		°C		
Storage temperature	T _{STG}	- 55 to +175			°C	



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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance	R _{θJL}	42	°C/W			
Junction-to-ambient thermal resistance	R _{eja}	76	°C/W			
Junction-to-case thermal resistance	R _{eJC}	45	°C/W			

Thermal Performance Note: Units mounted on recommended PCB (10mm x 10mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT		
	$I_F = 1.5A, T_J = 25^{\circ}C$	V _F	0.79	0.85	V		
Forward voltage per diode ⁽¹⁾	$I_F = 3A, T_J = 25^{\circ}C$		0.86	0.90	V		
	$I_F = 1.5A, T_J = 150^{\circ}C$		0.61	0.68	V		
	$I_F = 3A, T_J = 150^{\circ}C$		0.69	0.73	V		
	$T_J = 25^{\circ}C$		-	5	μA		
Reverse current @ rated V_R per diode ⁽²⁾	T _J = 150°C	I _R	-	150	μA		
Junction capacitance	1 MHz, V _R =4.0V	CJ	45	-	pF		
Reverse recovery time	I _F =0.5A,I _R =1.0A I _{RR} =0.25A	t _{rr}	-	25	ns		

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

DRDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
	I H	R5	G	SMB	850 / 7" Plastic reel	
MUR3xxSB		R4		SMB	3,000 / 13" Paper reel	
(Note 1, 2)		M4		SMB	3,000 / 13" Plastic reel	

Notes:

1. "xx" defines voltage from 50V (MUR305SB) to 200V (MUR320SB)

2. Whole series with green compound (halogen-free)

EXAMPLE					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING Code	PACKING CODE SUFFIX	DESCRIPTION
MUR320SBHR5	MUR320SB	Н	R5	G	Green compound AEC-Q101 qualified



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

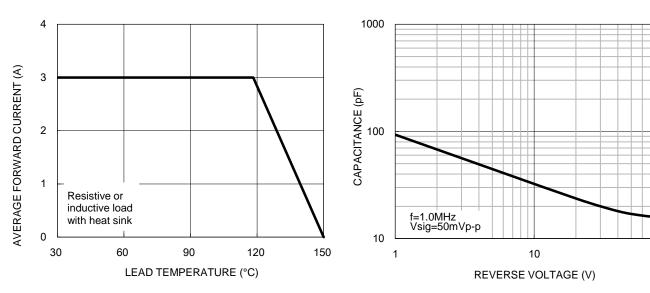
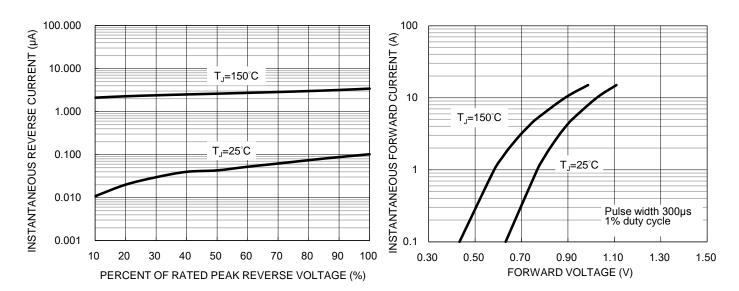


Fig.1 Forward Current Derating Curve

Fig.2 Typical Junction Capacitance

Fig.3 Typical Reverse Characteristics

Fig4. Typical Forward Characteristics



100

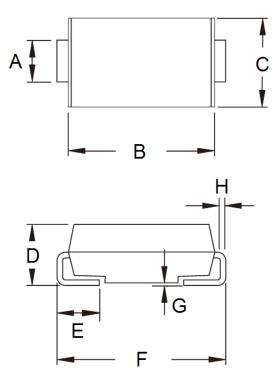


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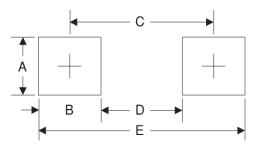
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM	Unit (mm)		Unit ((inch)
	Min	Max	Min	Max
А	1.95	2.20	0.077	0.087
В	4.05	4.60	0.159	0.181
С	3.30	3.95	0.130	0.156
D	1.95	2.65	0.077	0.104
E	0.75	1.60	0.030	0.063
F	5.10	5.60	0.201	0.220
G	0.05	0.20	0.002	0.008
Н	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	2.3	0.091
В	2.5	0.098
С	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



P/N = Marking Code

- G = Green Compound
- YW = Date Code
- F = Factory Code



MUR305SB - MUR320SB

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